# LEKOLED

### **3030 EMC LED Datasheet**



#### **Features:**

Top View White LED Thermally Enhanced Package Design High Luminous Flux Output High Current Capability Good Color Uniformity Compact Package Size, Small LES Enables Good Optic Design Enviromental Friendly; ROHS Compliance

### **Applications:**

Down Lights, Interior Lights General Lighting, LED Indoor Lights Flood Light, High Bay Light, Tunel Light and other LED Outdoor Lights



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#### **PRODUCT NAMING RULES**

LKL	XXX	ХХ	ХХ	Х	Х
LEKOLED	Туре	ССТ	RA	No. of series chip	No. of parallel chip
LKL	E30	W27: 2700K	R7: Ra70	8: 8S	1:1P
		W30: 3000K	R8: Ra80	2:25	
		W40: 4000K	R9: Ra90		
		W50: 5000K			
		W57: 5700K			
		W65: 6500K			

Х	Х	
Viewing Angle	Lighting Shape	
0: 120°/140°	R: Round LES	
	S: Square LES	



#### **CHARACTERISTICS**

SPECIFICATIONS (Ta=25℃)						
	Color	120mA		65mA		
Norminal CCT	Rendering	Efficacy (LM/W)	Luminous Flux	Efficacy (LM/W)	Luminous Flux	Part Number
	70	160	110-115LM	178	65-70LM	LKL-E30W27R7210R
2700K	80	148	100-110LM	164	60-65LM	LKL-E30W27R8210R
	90	125	80-90LM	138	50-55LM	LKL-E30W27R9210R
	70	163	115-120LM	180	65-70LM	LKL-E30W30R7210R
3000K	80	151	105-115LM	168	60-65LM	LKL-E30W30R8210R
	90	128	85-95LM	142	50-55LM	LKL-E30W30R9210R
	70	165	115-120LM	183	65-70LM	LKL-E30W35R7210R
3500К	80	157	105-115LM	174	62-66LM	LKL-E30W35R8210R
	90	130	85-95LM	145	52-56LM	LKL-E30W35R9210R
	70	169	120-125LM	188	68-72LM	LKL-E30W40R7210R
4000K	80	164	110-120LM	182	65-70LM	LKL-E30W40R8210R
	90	136	90-100LM	151	54-57LM	LKL-E30W40R9210R
	70	169	120-125LM	188	68-72LM	LKL-E30W50R7210R
5000K	80	164	110-120LM	182	65-70LM	LKL-E30W50R8210R
	90	136	90-100LM	151	54-57LM	LKL-E30W50R9210R
	70	169	120-125LM	188	68-72LM	LKL-E30W57R7210R
5700K	80	164	110-120LM	188	68-72LM	LKL-E30W57R8210R
	90	136	90-100LM	188	68-72LM	LKL-E30W57R9210R
	70	169	120-125LM	188	68-72LM	LKL-E30W65R7210R
6500K	80	164	110-120LM	188	68-72LM	LKL-E30W65R8210R
	90	136	90-100LM	188	68-72LM	LKL-E30W65R9210R



#### **CHARACTERISTICS**

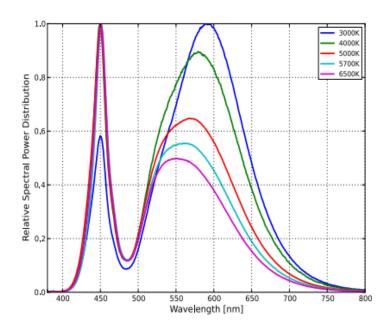
solute Maximum Ratings at Tj=25°C		
Parameters	Symbol	Maximum Performance
Forward Current	I <sub>F</sub>	240mA
Peak Pulsed Forward Current	I <sub>FP</sub>	300mA
Power Dissipation	P <sub>D</sub>	1050mW
Reverse Voltage	V <sub>R</sub>	5V
Viewing Angle	20 1/2	120°
Operating Temperature	T <sub>OPR</sub>	-40 ~ +105°C
Storage Temperature	T <sub>STG</sub>	-40 ~ +85°C
Junction Temperature	Tj	125°C
Soldering Temperature	T <sub>SLD</sub>	Reflow Soldering: 230°C or 260°C for 10Sec

#### Electrical/ Optical Characteristics at Tj=25°C

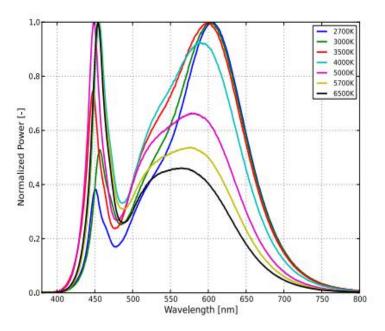
					-	
Parameters	Symbol	Min	Туре	Max	Unit	Condition
Forward Voltage	V <sub>F</sub>	5.8	6.1	6.6	V	IF=120mA
Reverse Current	IR			10	μΑ	VR=5V
Thermal Resistance	Rth j-sp		12		°C/W	IF=120mA
Electrostatic Discharge	ESD	1000			V	HBM

#### **RELATIVE SPECTRAL POWER DISTRIBUTION**

RA70 Min

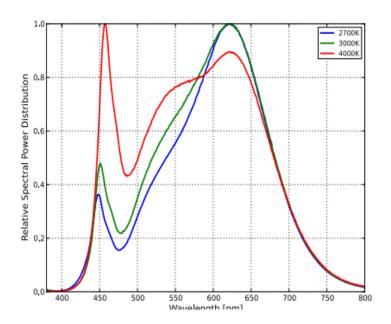


RA80 Min

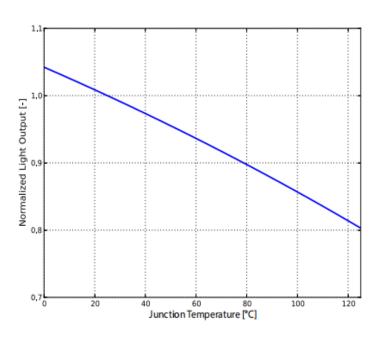


#### **RELATIVE SPECTRAL POWER DISTRIBUTION**

RA90 Min

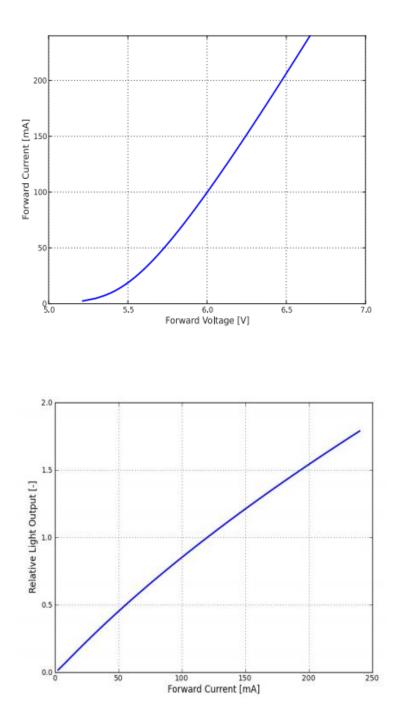


#### **TYPICAL CHARACTERISTIC CURVES**

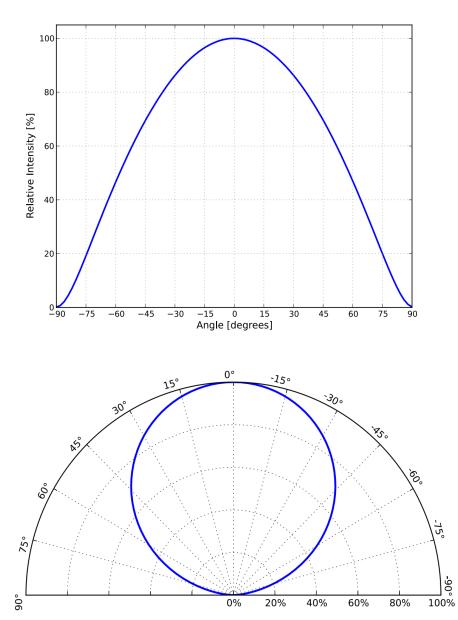


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#### **TYPICAL CHARACTERISTIC CURVES**

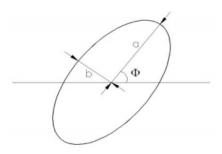


#### **TYPICAL CHARACTERISTIC CURVES**



**RADIATION PATTERN CHARACTERISRICS** 

#### **CIE BINNING INFORMATION**



#### The color ranks have chromaticity ranges within 5-step MacAdam ellipse

Color Code Center		Rad	Angle(deg)		
Color Code	x	У	а	b	Φ
27R5	0.4620	0.4145	0.013500	0.007000	53.42
30R5	0.4383	0.4081	0.013900	0.006800	53.13
35R5	0.4138	0.3983	0.015450	0.006900	54.00
40R5	0.3875	0.3868	0.015650	0.006700	53.43
50R5	0.3507	0.3635	0.013700	0.005900	59.37
57R5	0.3348	0.3491	0.011175	0.005500	58.35
65R5	0.3187	0.3363	0.011150	0.004750	58.34

\* Tolerance of measurements of the chromaticity Coordinate is ±0.005.



#### **RELIABILITY TESTS**

Test Items	Test Conditions	Sample QTY	Ac/Re
Aging Test	IF=120mA, Ta=25 ℃ x6000hrs	22	0/1
Aging Test	IF=120mA, Ta=85 ℃ x6000hrs	22	0/1
High Temperature Storage	<b>100</b> °C x1000hrs	22	0/1
Low Temperature Storage	-40°C x1000hrs	22	0/1
High Temp & Humidity	IF=120mA, 85 $^\circ \!\! \mathbb{C}$ , 85% RH for 6000hrs	22	0/1
Temperature Shock	-40°Cx30 min & +100°Cx30 min, 100cycle	22	0/1
ESD(HBM)	1000V HBM/ 1 Time	10	0/1

#### Criteria for Judging LED Failure (Tc= $25^{\circ}$ C)

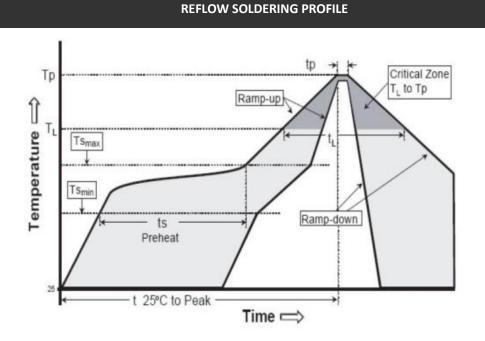
Items	Symbol	Test Conditions	Criteria for Judging LED Failure
Forward Voltage	VF	IF=120mA	>U x 1.1
Reverse Current	IR	VR=5V	IR>/= 10μA
Lumen	ΦV	IF=120mA	<s 0.7<="" td="" x=""></s>

U refers to max value; S refers to initial value.

Notes: Judging criteria based on Tc=25  $^\circ\!\mathrm{C}.$ 

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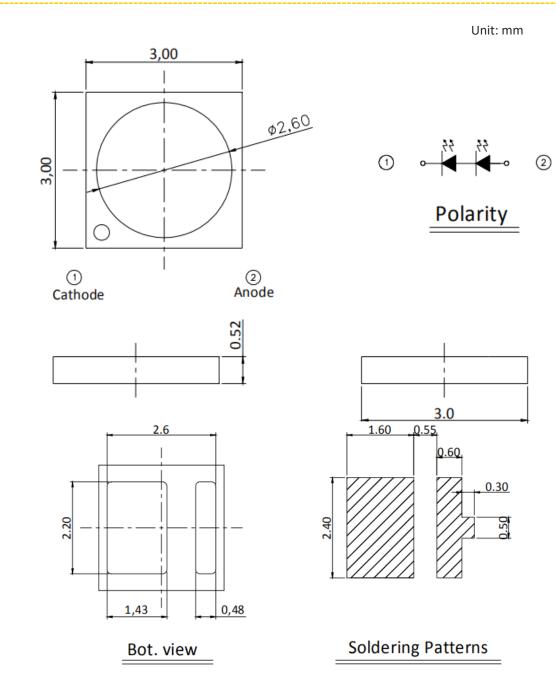
#### **TYPICAL CHARACTERISTIC CURVES**



Profile Features	Lead-free solder	Lead solder	Soldering by Manual
Ramp-up Speed(Ts max to Tp)	3 °C/ second max.	3 °C/ second max.	
Preheat: Min. Temperature(Tsmin)	150 °C	100 °C	
Preheat: Max.Temperature(Tsmax)	200 °C	150 °C	
Preheat: Time (tsmin to tsmax)	60~180 seconds	60~120 seconds	
Temperature to Keep: (TL)	217 °C	183 °C	Max. temperature: 350°C
Time to Keep: (tL)	60~150 seconds	60~150 seconds	3 seconds/1 time
Peak Temperature (Tp)	260 °C	215 °C	
temperature	20~40 seconds	10~30 seconds	
Ramp-down Speed	6°C/ second max.	6°C/ second max.	
Time to the peak Temperature	8 minutes max.	6 minutes max.	



#### DIMENSIONS



Notes :

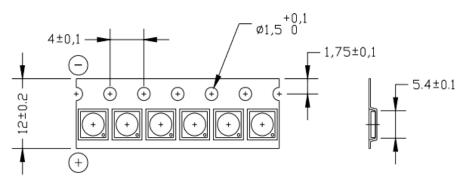
\*All dimensions are in millimeters.(tolerance:±0.1mm)

\*The appearance and specifications of the product may be changed for improvement without notice.

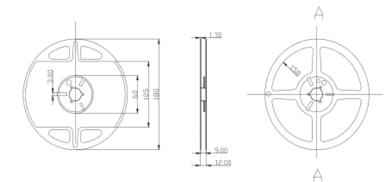
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#### PACKAGING

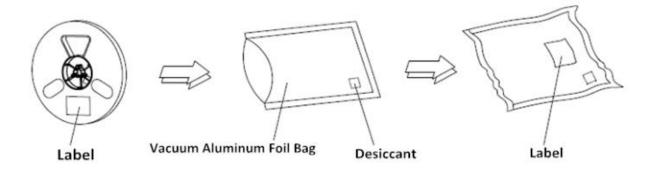
Tape Specifications (Units : mm) Package: 5000pcs per reel



**Reel Dimensions** 



#### Moisture Resistant Packaging



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#### PRECAUTIONS

#### Storage

- 1. Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to aminimum.
- 2. Before opening the package, the product should be kept at 30  $^\circ$ C or less and humidity less than 60% RH, and beused within a year.
- 3. After opening the package, the product should be stored at 30  $^{\circ}$ C or less and humidity less than 10%RH, and besoldered within 24 hrs (1day). It is recommended that the product be operated at the workshop condition of 30  $^{\circ}$ C or less and humidity less than 60%RH.
- 4. If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (80±5) ℃ for 24 hours.

#### **Static Electricity**

- 1. Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristic such as the forward voltage becomes lower, or the LEDs do not light at the low current. even not light.
- 2. All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or antielectrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.

#### Vulcanization

LED curing is due to sulfur being in bracket and the +1 price of silver in the chemical reaction generated Ag2S in the process. It will lead to the capacity of reflecting of silver layer reducing, light color temperature drift and serious decline ,seriously affecting the performance of the product. So we should take corresponding measures to avioding vulcanization, such as to avoid using sulphur volatile substances and keeping away from high sulphur content of the material.

#### **Design Consideration**

- In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen.
- 2. It is recommended to use Circuit A which regulates the current flowing through each LED rather than Circuit B.
- When driving LEDs with a constant voltage in Circuit B, the current through the LEDs may vary due to the variation in Forward Voltage (VF) of the LEDs. In the worst case, some LED may be subjected to stresses in excess of the Absolute Maximum Rating.



3. Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color changed and so on. Please consider the heat generation of the LEDs when making the system design.

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#### PRECAUTIONS

#### Safety Advice For Human Eyes

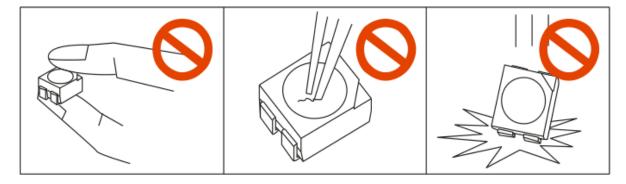
Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity will cause great hazard to human eyes. Please be careful.

#### The safe temperature for LEDs working

The high temperature will make the LEDs' Luminous Intensity decreased radically, if LEDs worked in hoteyes. Please be careful. environment for a long time, they will be disabled easily. When LEDs are working in a closed array, we suggest that the LEDs' surface temperature should be lower than 55  $^{\circ}$ C and the legs' temperature should be lower than 75  $^{\circ}$ C.

#### Others

1. When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to Die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



2. The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.